8th ESA Round Table on Micro and Nano Technologies for Space Applications, 15-18 October 2012

Electrical Characterisation of Gamma-ray Irradiated High-κ Metal-Insulator-Metal **Capacitors for Space Applications Evaluation** #2631229, 11.45am, Tuesday 16 October 2012 Session 4: Radiation & Miniaturisation **ESA/ESTEC**, Noordwijk, The Netherlands B.J.A. Hutchinson, I.M. Povey, B.J. Sheehan, E. Sheehan, O.Z. Olszewski, K. Cherkaoui, É. O'Connor, R. Duane, P.K. Hurley, and S. Monaghan*

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- Introduction
 - Why high-k capacitors?
 - Low-k dielectrics
 - High-*k* dielectric challenges
 - Barriers to high-k solutions
- <u>"MISO" high-k invention</u>
 - Patent application
 - o Electrical results
 - General properties
- Initial irradiation results
- Further irradiation research
- Conclusions and future plans



Tyndall III-V/Si Lab

Introduction Why high-*k* capacitors?

- $C_{tot} = n \times k \varepsilon_0 A / t$, $k \sim 4 k_0$
- $A_0/4=A$ for same C_{tot}
- Single MIM, *n*=1
- Capacitors could have
 - Integration capability
 - o Small surface area
 - Redundancy > 4×
 - Low power & weight







Introduction Why high-k capacitors?

- Stacked MIMs, *n*>1
- Small 2D surface footprint
- 3D MIM, *n*=1, *A*>>*A*₀
- Stacked 3D MIMs
 - n>1 and A>>A₀
- Smaller surface footprint
- Capacitors could have
- Integration capability
- Very small surface footprint
- o Redundancy >> 4×
- Low power & weight





Our MIM device mask



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Introduction Low-k dielectrics

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- **Positives** of low-*k* dielectrics...
 - o Low leakage, low loss, high breakdown, irradiation hard
 - High temperature stability and linear capacitance with V, f, & T
- Negatives of low-k dielectrics...
 - Low capacitance/charge/energy storage → Large area capacitors
 - Poor for scaling, integration, low power and redundancy



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High-*k* dielectric challenges

- Negatives of high-k dielectrics...
 - o Greater leakage, higher dielectric loss, and lower breakdown
 - o Low temperature instability and electrically poor when irradiated
 - Non-linearity of capacitance with V, f, & T
- **Positives** of high-*k* dielectrics...
 - High capacitance/charge/energy storage \rightarrow Small area capacitors
 - o Good for scaling, integration, low power and redundancy





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Introduction Barriers to high-*k* solutions

- High operational leakage
- Transport mechanism variability
- Soft-breakdown events
- Low hard-breakdown voltage
- Variability in breakdown voltage
- Electrically poor when irradiated





- Capacitance non-linearity ($\alpha >>$ 50*ppm/V*²) and injection asymmetry
- Frequency dispersion of capacitance
- High dielectric loss (low Q(f)-value)
- Low temperature instability <450°C
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"MISO" high-k invention Patent application

- Metal-in-silicon-oxide (MISO)
- Based on $M_x Si_{1-x}O_2$ system
- M = Hf and/or Zr
- Other elements possible
- Atomic Layer Deposition
- Patent in progress*
- CMOS compatible material
- Stable at high temperatures
- Non-contaminant system
- Structures, x, ALD processes

 Confidential until patent process is complete



Cambridge NanoTech Fiji ALD Tool

University College Cork's Invention of the Year 2010 in ICT Awarded: April 2011

*S. Monaghan and I. M. Povey, patent filed on 21 October 2011 (EPO#EP11186166.2; USPO#61549751)



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"MISO" high-k invention Electrical results



- JVs & CVs (insets) for as-deposited MIMs: (a) 300nm & (b) 100nm
- Leakage, breakdown, and general IV characteristics excellent
- Capacitance at 0V implies an effective *k*-value of ~15-16
- Linearity (α) is ~2.4/30 ppm/V² for (a) and (b) respectively



"MISO" high-k invention Electrical results



- As-deposited 130nm MIMs with Al electrodes: (a) CV (b) JV
- Capacitance at 0V implies an effective *k*-value of ~16-17
- Linearity (α) is ~15 ppm/V² and Q(f) > 50
- Leakage, breakdown, and general IV characteristics also excellent ₁₅



"MISO" high-k invention Electrical results



- As-deposited 50nm MIMs with TiW/Ti electrodes: (a) CV (b) JV
- J/BE excellent, general IV good, non-ideal interface effects in BV
- At \leq 55nm interface effects begin to dominate CV behaviour
- Improved interfaces required to reduce effect on α and ΔBV



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"MISO" high-k invention General properties

- Constant J, E_{BD} for all t = 2nm
 350nm this is not common for high-k dielectrics!
- High breakdown field ~ 7.5 MV/cm
- Low operating leakage ~1-5×10⁻⁸A/cm²
- No soft-breakdown & high temp stability









"MISO" high-k invention General properties

- Excellent repeatability
- CET v thickness linear
- Extracted *k*-value ~ 17
- Capacitance linearity
- Non-ideal interfaces



S. Monaghan and I. M. Povey, *Electronics Letters* **48** (4), 230 (2012)



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Initial irradiation results Summary

• 130nm Al/MISO/Al tested

Mean of total sampling at each voltage taken to get *t* versus BV

- Mean-Time-To-Failure (MTTF) ₁
- MTTF for control sample
- MTTF for 78krad sample
 - Zero bias irradiated

Irradiation conditions*

Control samples retained Gamma rays from ⁶⁰Co at 0V Total 16krad (210rad/min) Total 78krad (210rad/min)



*Thanks to ESA and co-authors OZO, RD



Initial irradiation results Summary

• Each point mean of 10¹⁸ 130nm Control sample sampling 130nm irradiated sample (78krad) 10¹⁶ Linear fit to control sample Mean-Time-To-Failure (s) Linear fit to irradiated sample (78krad) 10¹⁴ • Operating voltage = 40V 10¹² V_{op} 10¹⁰ • MTTF similar for both 10⁸ samples 10⁶ • Lifetime at 40V is ~1-3k 10⁴ From ~1,600 years to ~3,200 years 10² years 10⁰ 20 30 80 90 No degradation after 10 70 100 50 60 40 0 Voltage (V) irradiation



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Further irradiation research

Funding required for test expansion

- Develop an extended MIM sample matrix for a DoE
- Oxide thickness, area/perimeter ranges, anneals, etc.
- MISO MIM structures tested in ESA components
- Gamma irradiation again from ⁶⁰Co
- Bias devices for different V at different total doses
- Dose levels to test shielded LEO*/GEO** capability
- Higher dose levels to test unshielded LEO/GEO capability
- Maximise radiation variety to assess effects of
 - Trapped electrons and protons
 - Solar energetic particles
 - o Cosmic rays
 - Secondary radiation



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Conclusions and future plans

- A high-*k* material that remains stable at high CMOS temperatures
- CMOS process compatible and a non-contaminant
- Electrical properties constant with scaling from ~350 nm to ~2 nm
 - Constant k-value of ~17
 - Constant high breakdown field (~7.5 MV/cm)
 - Constant low leakage (~1-5×10⁻⁸A/cm² @ operating voltage)
 - Capacitance linearity with V, f, T (when bulk dominates)



Conclusions and future plans

- Presently working at increasing the ALD rate >4× for industry
- Research on going to boost *k*-value further & reduce interface effects
- Initial gamma irradiation tests (at 0V) show no effect on MIMs
- MTTF gives lifetime prediction of ~1-3k years at operating voltage
 - However, only 130nm investigated in a limited way so far
- Funding support needed for full irradiation testing
- Potential for integration, scaling, redundancy & low power



Go raibh maith agaibh! (Thank you all!)

Investing in your future



We acknowledge (1) the European Space Agency (ESA) for irradiation tests that were performed as part of the NPI activity between Tyndall-UCC and ESA on the reliability of RF MEMS capacitive switches; (2) INSPIRE (PRTLI5, HEA, NDP 2007-2013, and the ERDF) for the PhD funding support to co-author BJAH; and (3) Enterprise Ireland, via projects DIELECTRIKAPS (CF-2011-1700Y) and ALECTRIKA (CF-2012-2002)

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